



Product Change Notification

111991 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111991 - 00
Change Title: Intel® CABLE DOCSIS PRODUCTS
DNCE2300, DNCE2302, DNCE2400,
DNCE2410
PCN 111991-00, Product Material, Label
Date of Publication: January 9, 2013

Key Characteristics of the Change:

Product Material

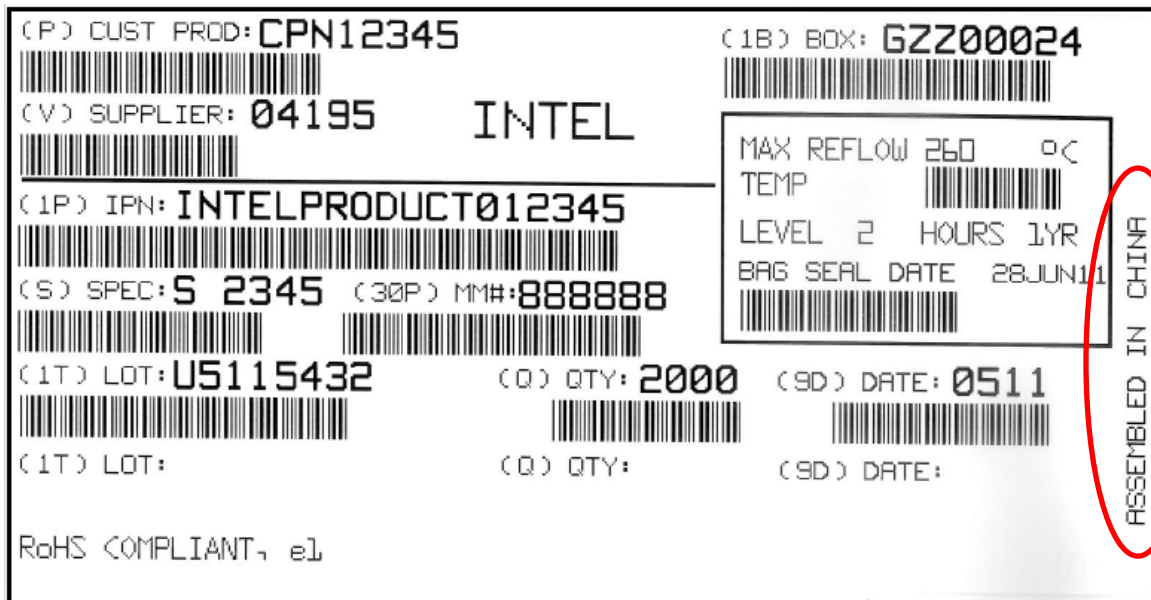
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 01, 2013
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Description of Change to the Customer:

In line with the acquisition of the cable modem division of Texas Instruments in November 2010, Intel is transferring the products listed in the products affected table from the existing TI supply chain to an Intel managed supply chain. This consolidation will enable Intel to provide better support to customers in the dynamic market environment.

This will be reflected by a change to the label/shipping documents, which will show the country of origin being China (See image below).



The above label is a representation for example purposes only. Actual label will reflect correct product data.

We will be moving the assembly/test location from the existing TI facility to an Intel managed subcontractor in China. As part of this transition we are changing the assembly material set to align with the Intel standard for this package type and location. The Intel standard material set is already qualified and in High Volume Manufacturing (HVM). In addition we will be conducting a qualification of the material set. The specific changes will include mold compound, die attach material, and copper wire with a thin palladium coating.

Customer Impact of Change and Recommended Action:

There is no change to the wafer/die, or to the substrate design or source. There will be no change to the package dimensions, or in the electrical or reliability performance of the device, and the change is equivalent in terms of form, fit and function.

Customers may receive product from either supply chain until existing inventory is depleted. There will be no change to the product order code.

Products Affected / Intel Ordering Codes:

Puma #	Base Nm	Marketing Name	Level 1	S Spec	Material Id	Corresponding TI Part #
Puma-3	CE2300	DNCE2300	DNCE2300S LHCE	S LHCE	911305	TNETC4600ZDW
		DNCE2302	DNCE2302S LHCF	S LHCF	911306	TNETC4602ZDW
Puma-4	CE2400	DNCE2400	DNCE2400S LHCG	S LHCG	911307	TNETC4700ZDW
		DNCE2410	DNCE2410S LHCH	S LHCH	911308	TNETC4710ZDW

PCN Revision History:

Date of Revision:
January 9, 2013

Revision Number:
00

Reason:
Originally Published PCN